

FIG. 1

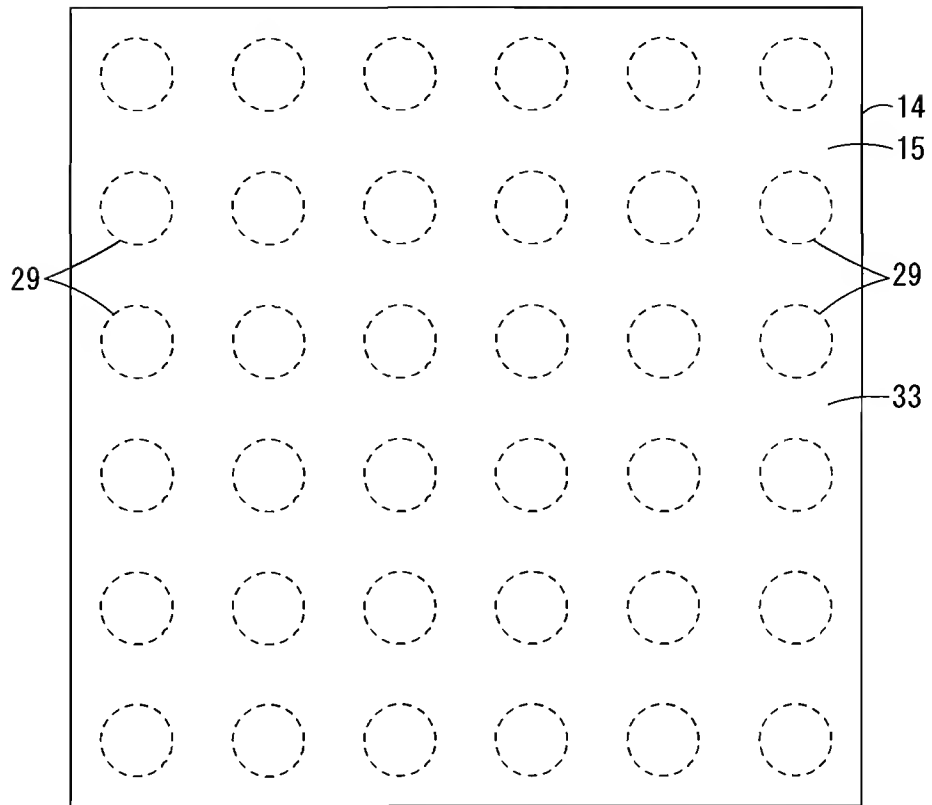


FIG. 2

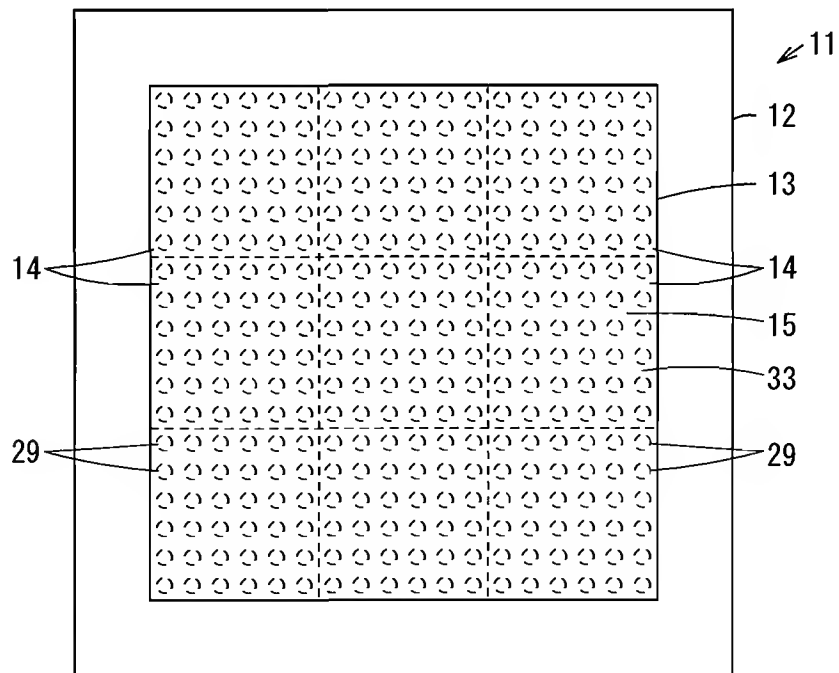


FIG. 3

ARRANGEMENT	COMBINATION EXAMPLE 1	COMBINATION EXAMPLE 2	COMBINATION EXAMPLE 3	COMBINATION EXAMPLE 4
LENS	ENGINEERING PLASTIC (100 TO 130°C)	ACRYLIC RESIN (120°C)	POLYPROPYLENE (110°C)	
ADHESIVE AGENT (THIRD INSULATING LAYER)	THERMOSETTING RESIN			
REFLECTOR	ENGINEERING PLASTIC (100 TO 130°C)	GLASS EPOXY RESIN	ALUMINUM	ALUMINUM NITRIDE
ADHESIVE AGENT (SECOND INSULATING LAYER)	THERMOSETTING RESIN			
CONDUCTIVE PATTERN	Au/Ni/Cu			
ADHESIVE AGENT (FIRST INSULATING LAYER)	THERMOSETTING RESIN			
SUBSTRATE	ALUMINUM	GLASS EPOXY RESIN	ALUMINUM NITRIDE	
LED	GaN-BASED LED			
DIE BONDING	Ag PASTE (150°C)	Au/Sn	Au	

FIG. 4

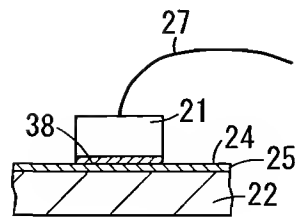


FIG. 5

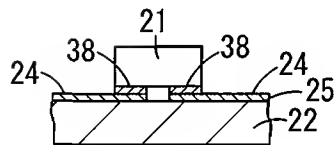


FIG. 6

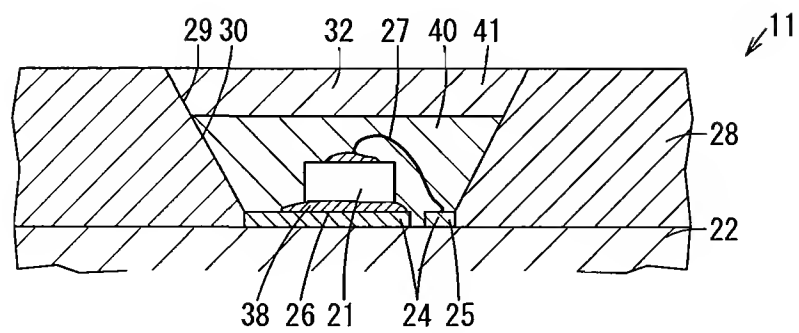


FIG. 7

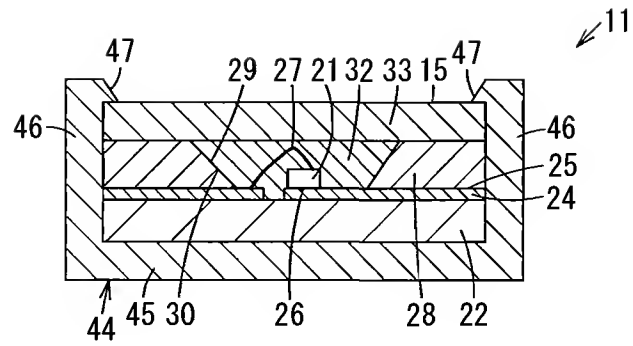


FIG. 8

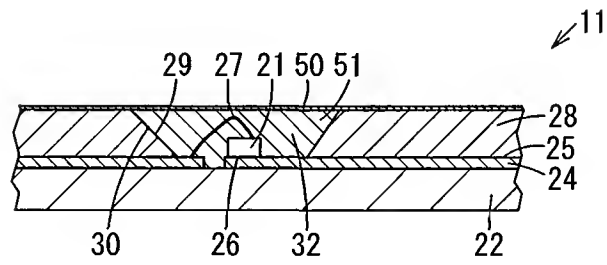


FIG. 9

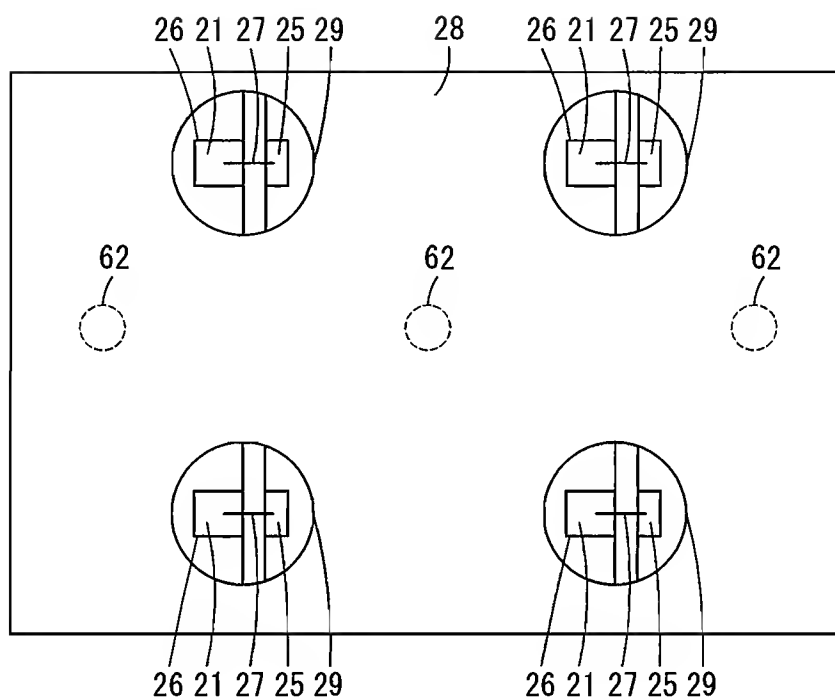


FIG. 10

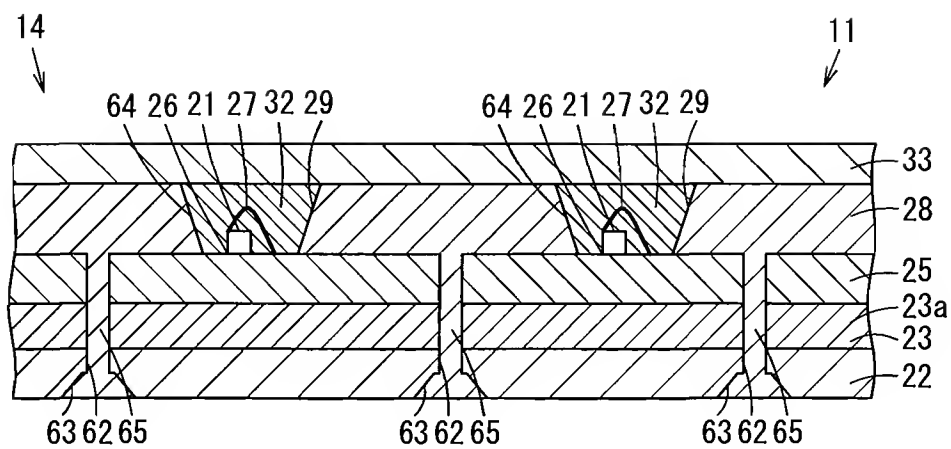


FIG. 11

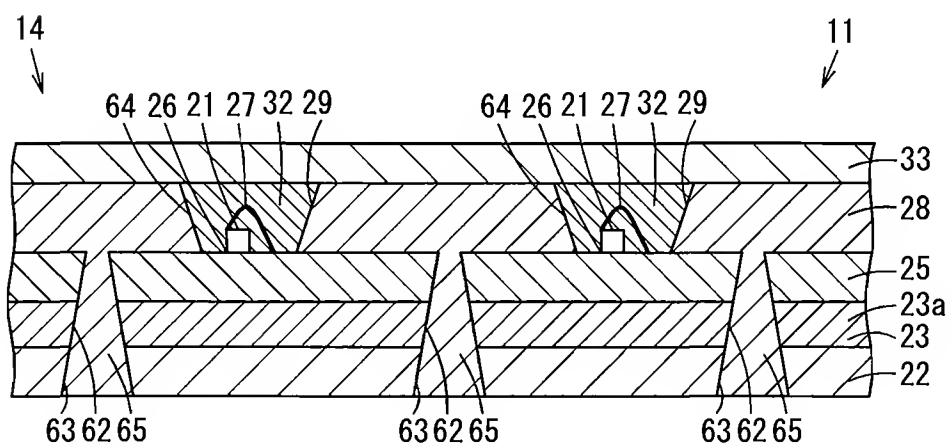


FIG. 12

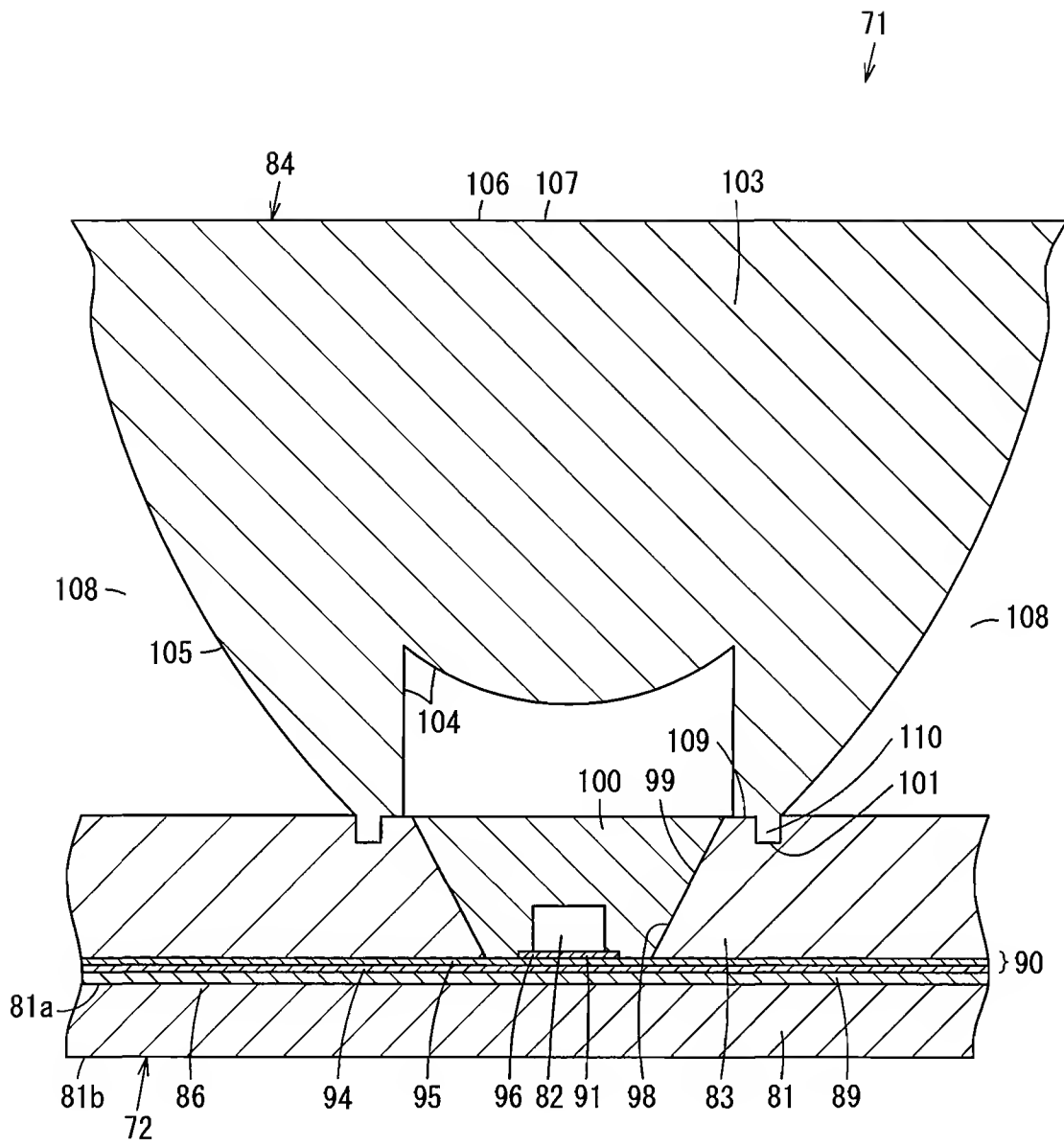


FIG. 13

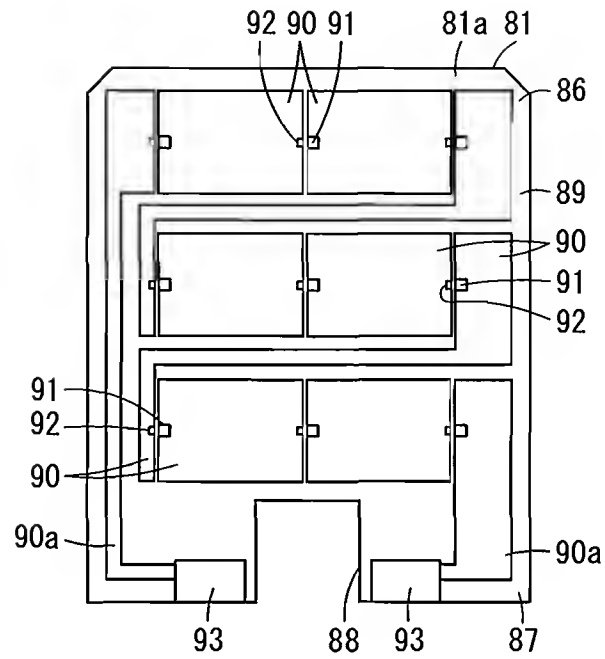


FIG. 14

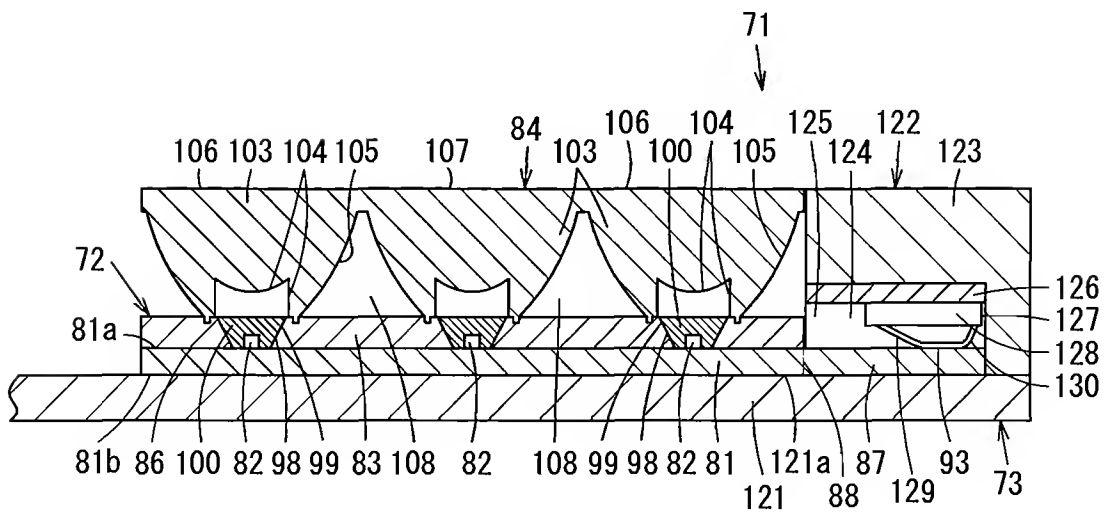


FIG. 15

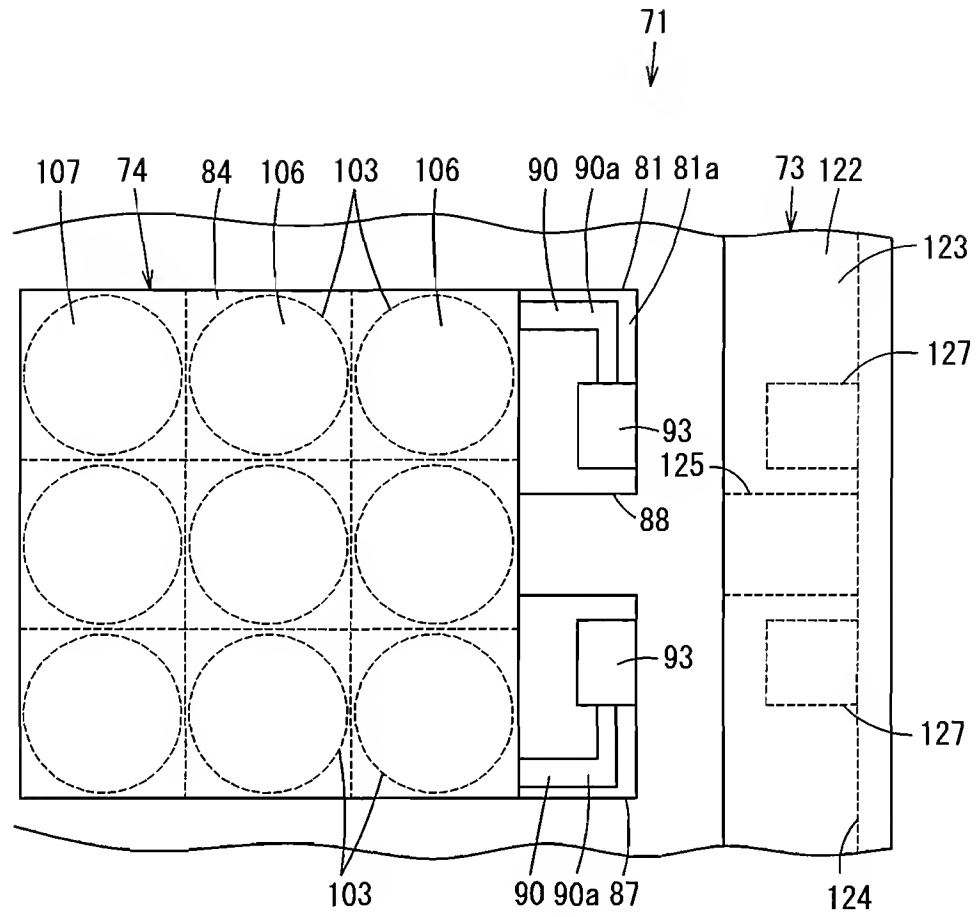


FIG. 16